FORM PTO-1595 1-31-92	R			SHEET	U.S. DEPARTMENT OF COMMERO Patent and Trademark Offi
		1017244	185	<del></del>	
To the Honorable Comm		<del>, _ , _ ,</del>	ase record the	attached original do	cuments or copy thereof.
1. Name of conveying party(ies): 05/15/0/ Shinichi NAKABAYASHI, Hisahiko ABE, Katsuhiro OTA			Name and address of receiving party(ies):     Name: Hitachi, Ltd.		
			Street A	ddress: 6, Kanda Sur	ugadai 4-chome, Chiyoda-ku
Additional name(s) of conveying party(ies) attached?  Yes No  3. Nature of conveyance:   Assignment  Merger   Security Agreement  Change of Name   Other   Execution Date: April 25,17, 2001			City:	Tokyo:	54578 154578
			Country	: Japan	Jc821 1
Execution Date. April 2	25,17, 2001		Additiona	l name(s) & address(es) at	ttached? 🔲 Yes 😨 No
4. Application number(s)  If this document is bei  A. Patent Appli	ng filed together w			date of the application	on is: April 25,17, 2001
		Additional numbers atta	ached? Yes	X No	
5. Name and address of p concerning document		espondence	6. Total nu	mber of applications	and patents involved: 1
Name: ANTONELLI	, TERRY, STOUT	& KRAUS, LLP	7. Total fee	e (37 CFR 3.41)	\$40.00
Internal Address:					charged to deposit account to deposit account
Street Address: 1300	North Seventeenth	Street	8. Deposit	account number: 01	-2135
Suite 1800 City: Arlington		p: 22209	(Attach du	plicate copy of this page	if paying by deposit account)
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9. Statement and signatur To the best of my of the original d  William I. Solomon Name of Person Signin Attorney Registration Total number of pages incl	y knowledge and be ocument. ng No. 28,565	William Signature	I A	nue and correct and a	ny attached copy is a true copy  May 15, 2001  Date
OMB No. 0651-0011 (ex	(p. 4/94)				

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## **ASSIGNMENT**

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## FABRICATION METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be grantey and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been mad;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

RECORDED: 05/15/2001

	INVENTOR(S)	Date Signed		
	(発明者フルネームサイン)	(署名日)		
1)	Shinichi Nakabalushi (Shinichi NAKABAYASHI)	25/APril/2001		
	Hisahiko Abe (Hisahiko ABE)	·		
3)	Katsuhiro (Matsuhiro OTA)	17/April/200/		
		·		
0)				

PATENT REEL: 011817 FRAME: 0436